

1. Record Nr.	UNINA9910458703703321
Titolo	Lead-free solder interconnect reliability [[electronic resource] /] / edited by Dongkai Shangguan
Pubbl/distr/stampa	Materials Park, OH, : ASM International, 2005
ISBN	1-61503-093-X
Descrizione fisica	1 online resource (302 p.)
Altri autori (Persone)	ShangguanDongkai <1963->
Disciplina	621.381/046
Soggetti	Microelectronic packaging - Reliability Solder and soldering Lead-free electronics manufacturing processes Electronic books.
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references and index.
Nota di contenuto	""Contents""; ""Foreword""; ""Preface""; ""Lead-Free Soldering and Environmental Compliance: An Overview""; ""Microstructural Evolution and Interfacial Interactions in Lead-Free Solder Interconnects""; ""Fatigue and Creep of Lead-Free Solder Alloys: Fundamental Properties""; ""Lead-Free Solder Joint Reliability Trends""; ""Chemical Interactions and Reliability Testing for Lead-Free Solder Interconnects""; ""Tin Whisker Growth on Lead-Free Solder Finishes""; ""Accelerated Testing Methodology for Lead-Free Solder Interconnects"" ""Thermomechanical Reliability Prediction of Lead-Free Solder Interconnects"" ""Design for Reliability Finite Element Modeling of Lead-Free Solder Interconnects""; ""Characterization and Failure Analyses of Lead-Free Solder Defects""; ""Reliability of Interconnects with Conductive Adhesives""; ""Lead-Free Solder Interconnect Reliability Outlook""; ""Index""